

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Sia Kim Tan</td> <td>09/10/2004</td> </tr> <tr> <td>Soon Yoeng Tan</td> <td>09/21/2004</td> </tr> <tr> <td>Qunying Lin</td> <td>09/10/2004</td> </tr> <tr> <td>Huey Ming Chong</td> <td>09/10/2004</td> </tr> <tr> <td>Liang-Choo Hsia</td> <td>09/10/2004</td> </tr> </tbody> </table>		Name	Execution Date	Sia Kim Tan	09/10/2004	Soon Yoeng Tan	09/21/2004	Qunying Lin	09/10/2004	Huey Ming Chong	09/10/2004	Liang-Choo Hsia	09/10/2004
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Liang-Choo Hsia	09/10/2004												
RECEIVING PARTY DATA													
Name:	CHARTERED SEMICONDUCTOR MANUFACTURING LTD.												
Street Address:	60 Woodlands Industrial Park D												
Internal Address:	Street 2												
City:	Singapore 738406												
State/Country:	SINGAPORE												
PROPERTY NUMBERS Total: 1													
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>10970077</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	10970077								
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CORRESPONDENCE DATA													
Fax Number:	(408)738-0881												
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>													
Phone:	408-738-0592												
Email:	efiling@ishimarulaw.com												
Correspondent Name:	Mikio Ishimaru												
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Address Line 4:	Sunnyvale, CALIFORNIA 94087												
NAME OF SUBMITTER:	Mikio Ishimaru												

CH \$40.00 10970077

Total Attachments: 4

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**PATENT
 REEL: 015737 FRAME: 0549**

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ASSIGNMENT

WHEREAS, the undersigned (hereinafter termed Assignor(s)) has/have invented certain new and useful improvements in

METHOD AND APPARATUS FOR REMOVING RADIATION SIDE LOBES


for which a United States patent application has been executed on or before the date of this assignment.

WHEREAS, CHARTERED SEMICONDUCTOR MANUFACTURING LTD., a Corporation of the Republic of Singapore, having a place of business at 60 Woodlands Industrial Park D, Street 2, Singapore 738406, Singapore (hereinafter termed Assignee), is desirous of acquiring the entire right, title and interest in and to said application and said invention and improvements thereon, and in and to Letters Patents thereon when granted in the United States and foreign countries.

NOW, THEREFORE, for good and valuable consideration received by said Assignor(s) from said Assignee, the receipt of which is hereby acknowledged by said Assignor(s):

1. Said Assignor(s) does hereby sell, assign, transfer and convey unto said Assignee, the entire right, title and interest in and to said application and said invention and in and to any and all improvements on said invention and in and to any and all improvements on said invention heretofore or hereafter made or acquired by said Assignor(s); and in and to any and all Letters Patent on said invention and/or said improvements that may be granted in the United States or any foreign country, including each and every Letters Patent granted on any application which is a division, continuation, substitution, renewal, or continuation-in-part of any said application, and in and to each and every reissue or extension of said Letters Patent.
2. Said Assignor(s) hereby covenants and agrees to cooperate with said Assignee where said Assignee may enjoy to the fullest extent the right, title and interest herein conveyed. Such cooperation shall include (a) prompt execution of all papers (prepared at the expense of Assignee) which are deemed necessary or desirable by Assignee to perfect in it the right, title and interest herein conveyed, (b) prompt execution of all petitions, oaths, specifications or other papers (prepared at the expense of Assignee) which are deemed necessary or desirable by assignee for prosecuting said application, for filing and prosecuting divisional, continuation, substitution, renewal, continuation-in-part, or additional applications in the United States and/or foreign countries covering said invention and/or said improvements, for filing and prosecuting applications for reissuance of letters patent included herein, or for interference proceedings involving said invention and/or said improvements and (c) prompt assistance and cooperation in the prosecution of interference proceedings involving said invention and/or said improvements and in the adjudication of said Letters Patent, particularly by the disclosure of facts and the production of evidence relating to said invention and/or said improvements, provided the expenses which may be incurred by said Assignor(s) in lending such assistance and cooperation shall be paid by the Assignee.
3. The terms, covenants and conditions of this assignment shall inure to the benefit of said Assignee, its successors, assigns and/or other legal representatives and shall be binding upon said Assignor(s), his/her heirs, legal representatives and assigns.
4. Said Assignor(s) hereby warrants and represents that he/she has not entered into any assignment, contract or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.



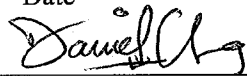
 Sia Kim Tan

 Witness Signature
 Lau Chiau Yen

 Print Witness Name
 10-9-04

 Date

10 SEP 2004

 Date


 Witness Signature
 CHONG KIEN SEEN DANIEL

 Print Witness Name
 10-9-04

 Date

 Soon Yoeng Tan

 Witness Signature

 Print Witness Name


 Date

 Date

 Witness Signature

 Print Witness Name

 Date



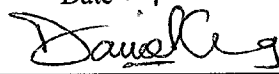
 m.l. ~~Qun Ying Lin~~ Qunying Lin
 2/21/05

 Witness Signature
 Lau Chiau Yen

 Print Witness Name
 10-9-04

 Date

1019104

 Date



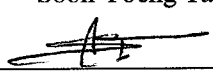

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 CHONG KIEN SEEN DANIEL

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 10-9-04

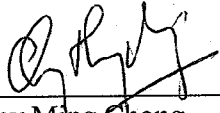
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
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_____	_____
Sia Kim Tan	Date
_____	_____
Witness Signature	Witness Signature
_____	_____
Print Witness Name	Print Witness Name
_____	_____
Date	Date

_____	_____
	21 September 2004
Soon Yoeng Tan	Date
_____	_____
	
Witness Signature	Witness Signature
_____	_____
LIEN SAN LEONG	Jeffrey Chue
Print Witness Name	Print Witness Name
_____	_____
21 Sep 2004	21 Sep 2004
Date	Date

_____	_____
Qun Ying Lin	Date
_____	_____
Witness Signature	Witness Signature
_____	_____
Print Witness Name	Print Witness Name
_____	_____
Date	Date




 Huey Ming Chong


 Witness Signature
 Lau Chian Yen

 Print Witness Name
 10-9-04

 Date


10-9-04


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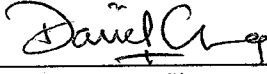
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 M.J. 2/21/05


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 Date

10-Sept-04

 Date


 Witness Signature
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